DECEMBER 1983-REVISED MARCH 1988

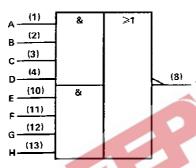
- Package Options Include "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

#### description

These devices contain 2-wide 4-input AND-OR-INVERT gates. They perform the Boolean function  $Y = \overline{ABCD + EFGH}$ .

The SN54LS55 is characterized for operation over the full military temperature range of  $-55\,^{\circ}\text{C}$  to  $125\,^{\circ}\text{C}$ . The SN74LS55 is characterized for operation from  $0\,^{\circ}\text{C}$  to  $70\,^{\circ}\text{C}$ .

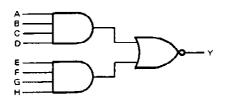
## logic symbol†



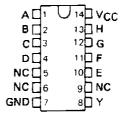
positive logic:  $Y = \overline{ABCD + EFGH}$ 

Pin numbers shown are for D, J, N, and W packages.

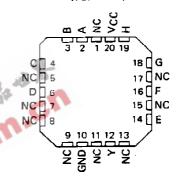
#### logic diagram



#### SN54LS55 . . . J OR W PACKAGE SN74LS55 . . . D OR N PACKAGE (TOP VIEW)

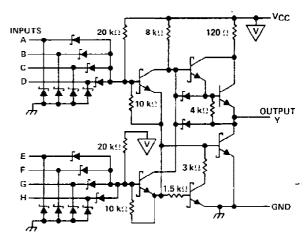


# SN54LS55 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### schematic



Resistor values shown are nominal.

<sup>&</sup>lt;sup>†</sup>This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

# SN54LS55, SN74LS55 2-WIDE 4-INPUT AND-OR-INVERT GATES

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note	<del>)</del> 1),,,,,,,,,,,,,,,,,,,,,,,,,,,	
Input voltage		
Operating free-air temperature:	SN54LS55	~55°C to 125°C
	SN74LS55	0°C to 70°C
Storage temperature range		-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		S	SN54LS55			SN74LS55		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
νcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>1H</sub>	High-level input voltage	2			2		_	V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current		_	~ 0.4			- 0.4	mA
loL	Low-level output current		43	4	L		8	mΑ
TA	Operating free-air temperature	<b>– 55</b>	ID.	125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	\$N54L\$55		SN74LS55			
	TEST CONDITIONS.	MIN TYP	MAX	MIN	TYP\$	MAX	UNIT
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA		- 1.5			1.5	V
Voн	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, I <sub>OH</sub> = -0.4 mA	2.5 3.4		2.7	3.4		V
Va.	$V_{CC} = MIN$ , $V_{1H} = 2 V$ , $I_{OL} = 4 mA$	0.25	0.4		0.25	0.4	V
VOL	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 8 mA				0.35	0.5	
Ιį	$V_{CC} = MAX$ , $V_{\parallel} = 7 V$		0.1	<u> </u>	_	0.1	mΑ
11н	V <sub>CC</sub> = MAX. V <sub>I</sub> = 2.7 V	_	20			20	ДД
ΗL	$V_{CC} = MAX$ , $V_1 = 0.4 V$		- 0.4	ſ		0.4	mΑ
los§	VCC = MAX	- 20	100	- 20		- 100	mΑ
ГССН	VCC = MAX, VI = 0 V	0.4	8.0		0.4	0.8	mΑ
ICCL	VCC = MAX, See Note 2	0.7	1.3		0.7	1.3	mΑ

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN TYP	MAX	UNIT
<sup>t</sup> PLH	Any	· ×	$R_1 \approx 2 k\Omega$ , $C_1 = 15 pF$	12	20	ns
<sup>t</sup> PHL	,,,,,	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		12.5	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_{\Delta} = 25^{\circ} \text{ C}$ .

<sup>§</sup>Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second. NOTE 2: All outputs of one AND gate at 4.5 V, all others at GND.

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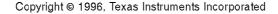
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